

Silicon Carbide (SiC) MOSFET – EliteSiC, 28 mohm, 1700 V, M1, TO-247-4L

NTH4L028N170M1

Features

- Typ. $R_{DS(on)}$ = 28 m Ω @ V_{GS} = 20 V
- Ultra Low Gate Charge ($Q_{G(tot)}$ = 200 nC)
- High Speed Switching with Low Capacitance (C_{oss} = 200 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Typical Applications

- UPS
- DC-DC Converter
- Boost Converter

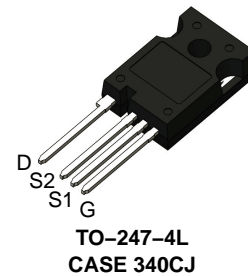
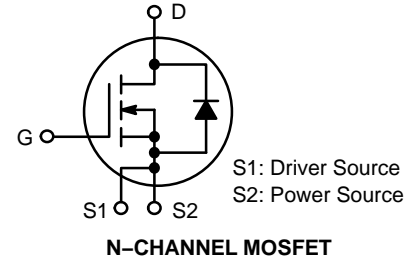
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

| Parameter | | Symbol | Value | Unit | |
|--|--------------------------|---|-------------|------|---|
| Drain-to-Source Voltage | | V_{DSS} | 1700 | V | |
| Gate-to-Source Voltage | | V_{GS} | -15/+25 | V | |
| Recommended Operation Values of Gate-to-Source Voltage | | $T_C < 175^\circ\text{C}$ V_{GSop} | -5/+20 | V | |
| Continuous Drain Current (Note 1) | Steady State | $T_C = 25^\circ\text{C}$ | I_D | 81 | A |
| | | | P_D | 535 | W |
| Continuous Drain Current (Note 1) | Steady State | $T_C = 100^\circ\text{C}$ | I_D | 57 | A |
| | | | P_D | 267 | W |
| Pulsed Drain Current (Note 2) | $T_C = 25^\circ\text{C}$ | | I_{DM} | 363 | A |
| Operating Junction and Storage Temperature Range | | T_J, T_{stg} | -55 to +175 | °C | |
| Source Current (Body Diode) | | I_S | 124 | A | |
| Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)}$ = 30 A, L = 1 mH) (Note 3) | | E_{AS} | 450 | mJ | |
| Maximum Lead Temperature for Soldering (1/8" from case for 5 s) | | T_L | 300 | °C | |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. Repetitive rating, limited by max junction temperature.
3. EAS of 450 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 30 A, V_{DD} = 120 V, V_{GS} = 18 V.

| $V_{(BR)DSS}$ | $R_{DS(ON)}$ MAX | I_D MAX |
|---------------|----------------------|-----------|
| 1700 V | 40 m Ω @ 20 V | 81 A |



MARKING DIAGRAM



H4L028N170M1 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|-----------|-----------------|
| NTH4L028N170M1 | TO-247-4L | 30 Units / Tube |

NTH4L028N170M1

THERMAL CHARACTERISTICS

| Parameter | Symbol | Max | Unit |
|--|-----------------|------|------|
| Junction-to-Case – Steady State (Note 1) | $R_{\theta JC}$ | 0.28 | °C/W |

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

OFF CHARACTERISTICS

| | | | | | | | |
|---|-------------------|--|---------------------------|------|---------|---------------|---------------|
| Drain-to-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$ | 1700 | – | – | V | |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | $V_{(BR)DSS}/T_J$ | $I_D = 1\text{ mA}$, referenced to 25°C | – | 0.46 | – | V/°C | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{GS} = 0\text{ V}, V_{DS} = 1700\text{ V}$ | $T_J = 25^\circ\text{C}$ | – | – | 100 | μA |
| | | | $T_J = 175^\circ\text{C}$ | – | – | 1 | mA |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{GS} = +25/-15\text{ V}, V_{DS} = 0\text{ V}$ | – | – | ± 1 | μA | |

ON CHARACTERISTICS (Note 2)

| | | | | | | | |
|-------------------------------|--------------|---|---------------------------|------|-----|----|------------|
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 20\text{ mA}$ | 1.8 | 2.75 | 4.3 | V | |
| Recommended Gate Voltage | V_{GOP} | | –5 | – | +20 | V | |
| Drain-to-Source On Resistance | $R_{DS(on)}$ | $V_{GS} = 20\text{ V}, I_D = 60\text{ A}, T_J = 25^\circ\text{C}$ $V_{GS} = 20\text{ V}, I_D = 60\text{ A}, T_J = 175^\circ\text{C}$ | $T_J = 25^\circ\text{C}$ | – | 28 | 40 | m Ω |
| | | | $T_J = 175^\circ\text{C}$ | – | 57 | – | |
| Forward Transconductance | g_{FS} | $V_{DS} = 20\text{ V}, I_D = 60\text{ A}$ | – | 31 | – | S | |

CHARGES, CAPACITANCES & GATE RESISTANCE

| | | | | | | |
|------------------------------|--------------|---|---|------|---|----------|
| Input Capacitance | C_{ISS} | $V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 800\text{ V}$ | – | 4230 | – | pF |
| Output Capacitance | C_{OSS} | | – | 200 | – | |
| Reverse Transfer Capacitance | C_{RSS} | | – | 10 | – | |
| Total Gate Charge | $Q_{G(TOT)}$ | $V_{GS} = -5/20\text{ V}, V_{DS} = 800\text{ V}, I_D = 60\text{ A}$ | – | 200 | – | nC |
| Gate-to-Source Charge | Q_{GS} | | – | 77 | – | |
| Gate-to-Drain Charge | Q_{GD} | | – | 46 | – | |
| Gate-Resistance | R_G | $f = 1\text{ MHz}$ | – | 5.8 | – | Ω |

SWITCHING CHARACTERISTICS

| | | | | | | |
|-------------------------|--------------|---|---|------|---|---------------|
| Turn-On Delay Time | $t_{d(ON)}$ | $V_{GS} = -5/20\text{ V}, V_{DS} = 1200\text{ V}, I_D = 60\text{ A}, R_G = 2\text{ }\Omega$ inductive load | – | 47 | – | ns |
| Rise Time | t_r | | – | 18 | – | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | – | 121 | – | |
| Fall Time | t_f | | – | 13 | – | μJ |
| Turn-On Switching Loss | E_{ON} | | – | 1311 | – | |
| Turn-Off Switching Loss | E_{OFF} | | – | 683 | – | |
| Total Switching Loss | E_{tot} | | – | 1994 | – | |

SOURCE-DRAIN DIODE CHARACTERISTICS

| | | | | | | |
|--|-----------|--|---|-----|-----|----|
| Continuous Source-Drain Diode Forward Current | I_{SD} | $V_{GS} = -5\text{ V}, T_J = 25^\circ\text{C}$ | – | – | 124 | A |
| Pulsed Source-Drain Diode Forward Current (Note 2) | I_{SDM} | | – | – | 363 | |
| Forward Diode Voltage | V_{SD} | $V_{GS} = -5\text{ V}, I_{SD} = 60\text{ A}, T_J = 25^\circ\text{C}$ | – | 4.3 | – | V |
| Reverse Recovery Time | t_{RR} | $V_{GS} = -5/20\text{ V}, I_{SD} = 60\text{ A}, di_S/dt = 1000\text{ A}/\mu\text{s}$ | – | 34 | – | ns |
| Reverse Recovery Charge | Q_{RR} | | – | 263 | – | nC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

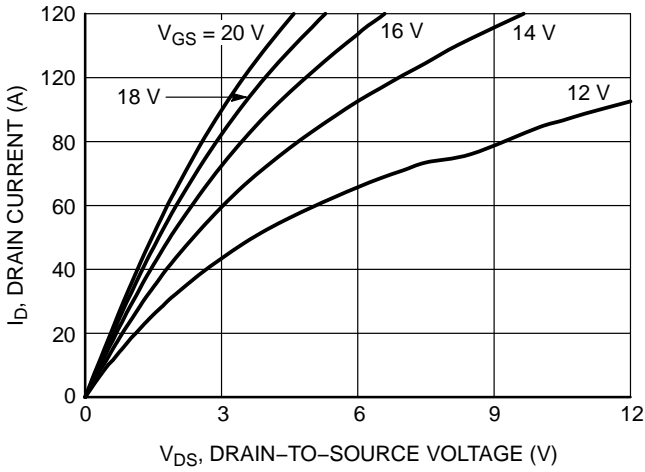


Figure 1. On-Region Characteristics

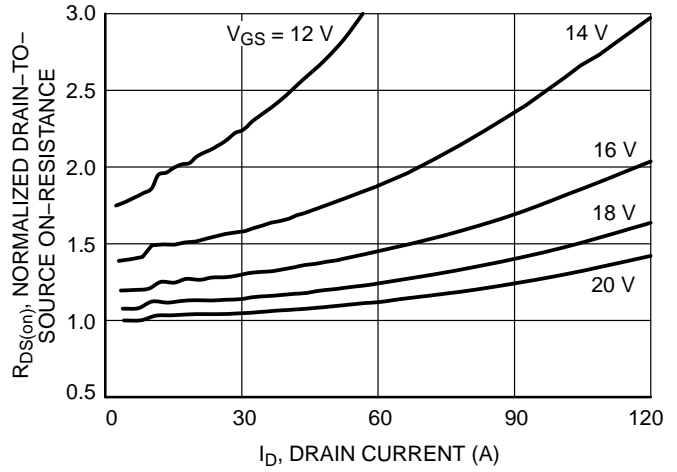


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

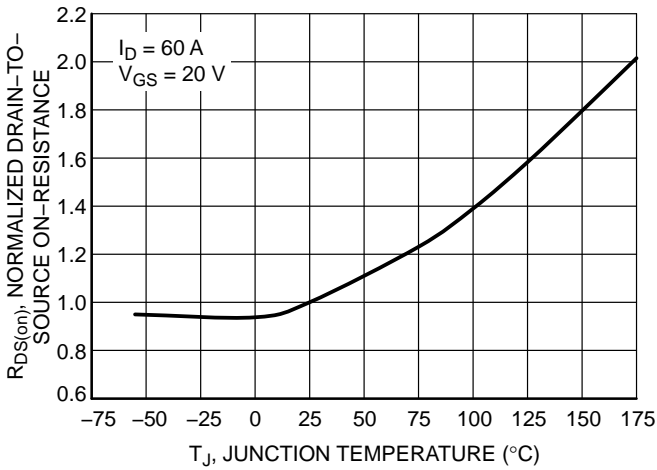


Figure 3. On-Resistance Variation with Temperature

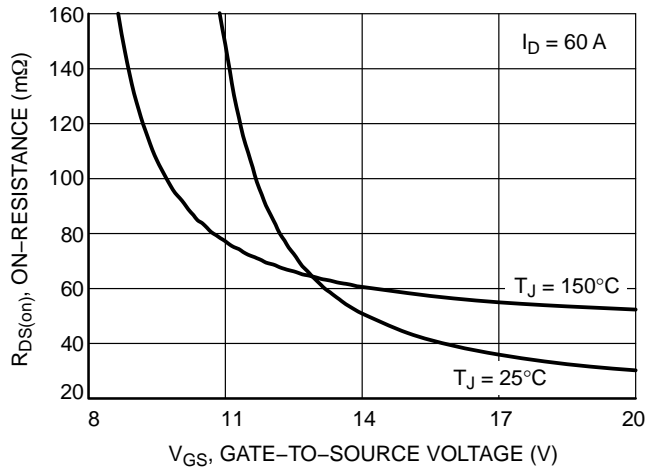


Figure 4. On-Resistance vs. Gate-to-Source Voltage

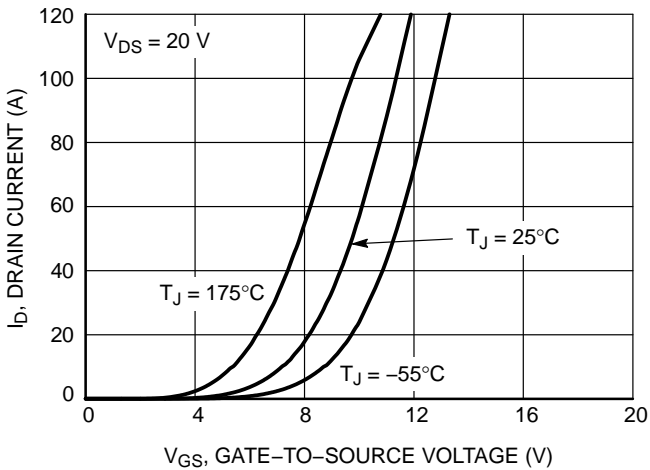


Figure 5. Transfer Characteristics

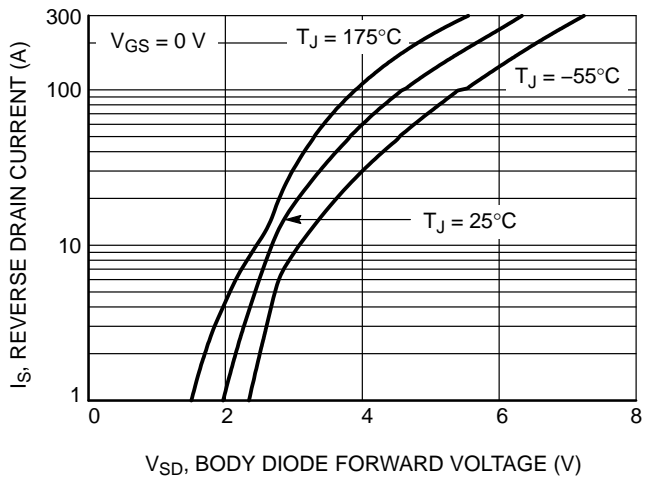


Figure 6. Diode Forward Voltage vs. Current

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TYPICAL CHARACTERISTICS

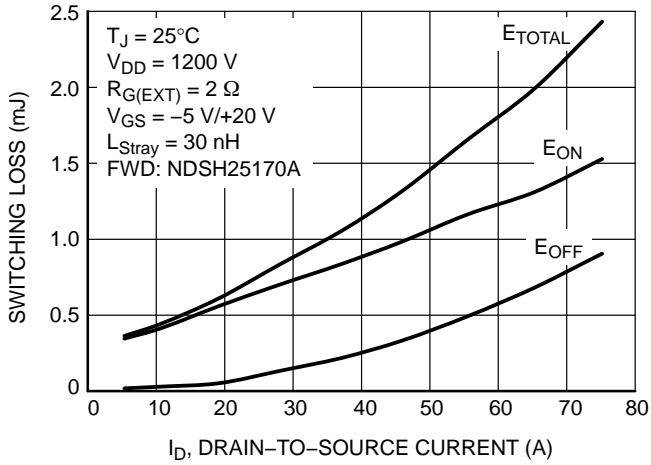


Figure 7. Switching Loss vs. Drain-to-Source Current (25°C)

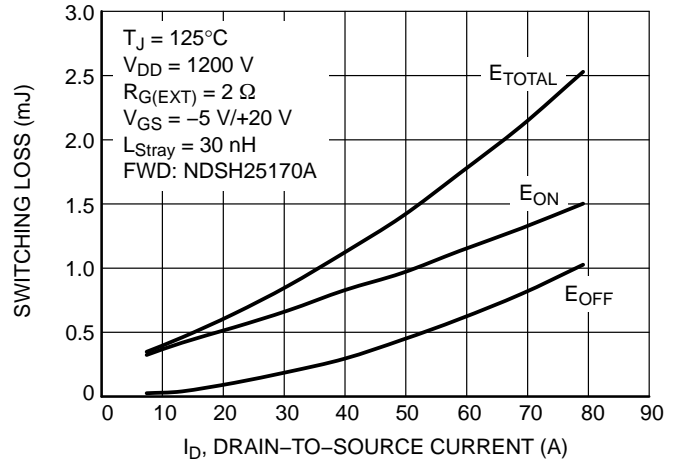


Figure 8. Switching Loss vs. Drain-to-Source Current (125°C)

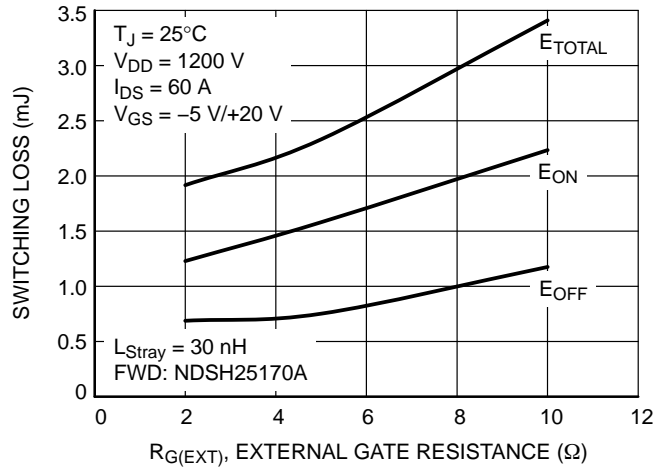


Figure 9. Switching Loss vs. External Gate Resistance

TYPICAL CHARACTERISTICS

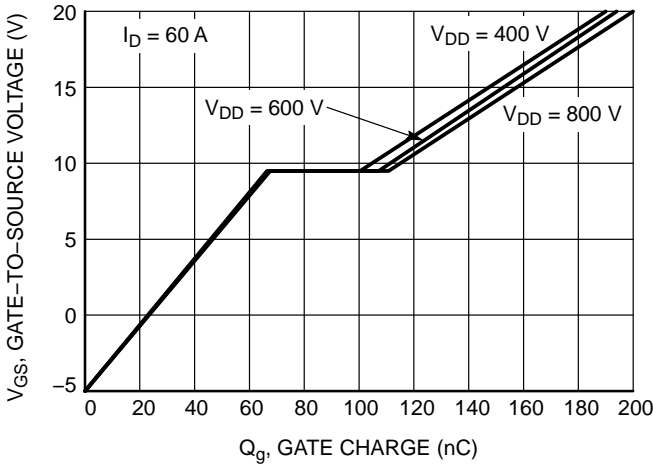


Figure 10. Gate-to-Source Voltage vs. Total Charge

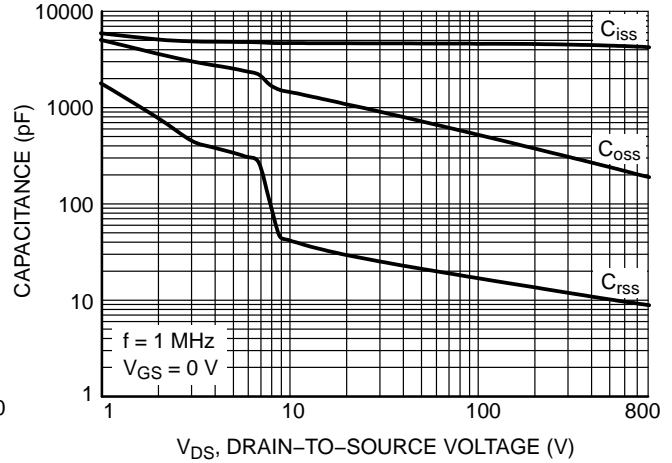


Figure 11. Capacitance vs. Drain-to-Source Voltage

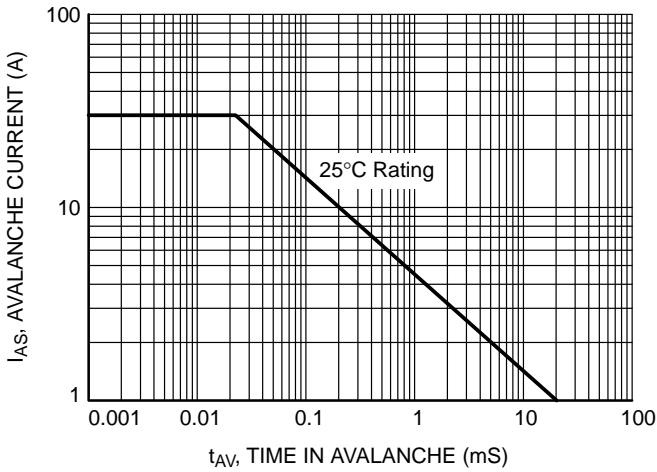


Figure 12. Unclamped Inductive Switching Capability

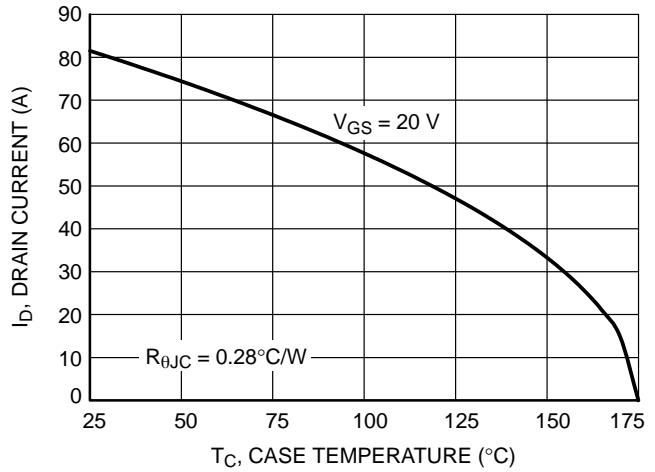


Figure 13. Maximum Continuous Drain Current vs. Case Temperature

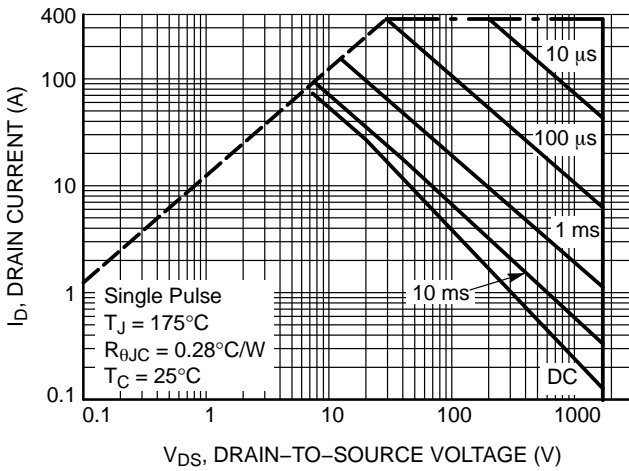


Figure 14. Safe Operating Area

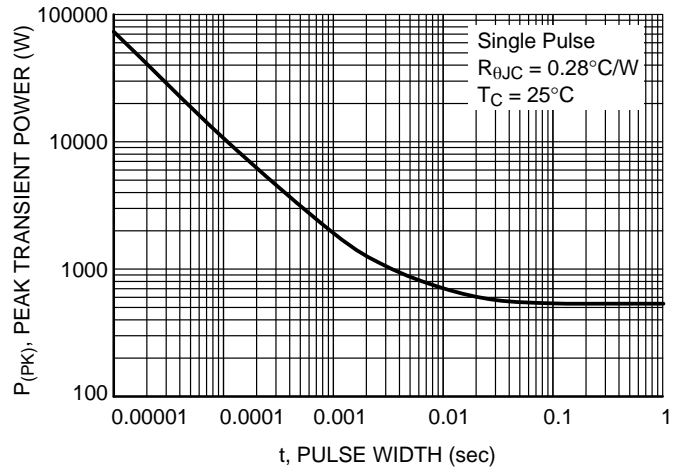


Figure 15. Single Pulse Maximum Power Dissipation

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TYPICAL CHARACTERISTICS

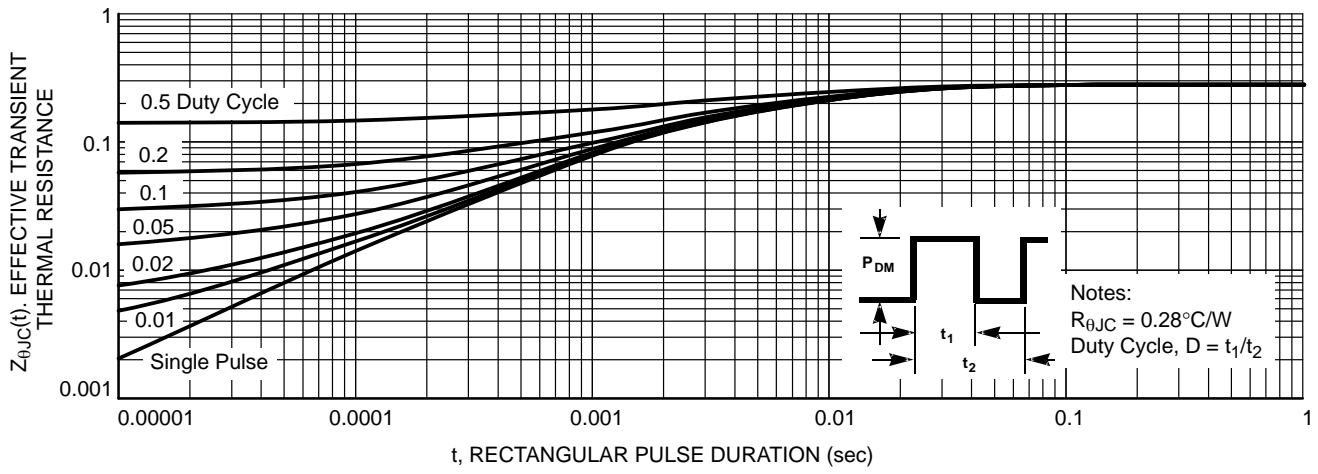


Figure 16. Junction-to-Case Thermal Response

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



TO-247-4LD
CASE 340CJ
ISSUE A

DATE 16 SEP 2019



| DIM | MILLIMETERS | | |
|-----|-------------|-------|-------|
| | MIN | NOM | MAX |
| A | 4.80 | 5.00 | 5.20 |
| A1 | 2.10 | 2.40 | 2.70 |
| A2 | 1.80 | 2.00 | 2.20 |
| b | 1.07 | 1.20 | 1.33 |
| b1 | 1.20 | 1.40 | 1.60 |
| b2 | 2.02 | 2.22 | 2.42 |
| c | 0.50 | 0.60 | 0.70 |
| D | 22.34 | 22.54 | 22.74 |
| D1 | 16.00 | 16.25 | 16.50 |
| D2 | 0.97 | 1.17 | 1.37 |
| e | 2.54 BSC | | |
| e1 | 5.08 BSC | | |
| E | 15.40 | 15.60 | 15.80 |
| E1 | 12.80 | 13.00 | 13.20 |
| E/2 | 4.80 | 5.00 | 5.20 |
| L | 18.22 | 18.42 | 18.62 |
| L1 | 2.42 | 2.62 | 2.82 |
| p | 3.40 | 3.60 | 3.80 |
| p1 | 6.60 | 6.80 | 7.00 |
| Q | 5.97 | 6.17 | 6.37 |
| S | 5.97 | 6.17 | 6.37 |

NOTES:

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- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5-2009.

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